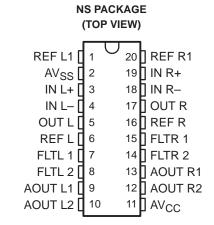
SLAS123B - MARCH 1995 - REVISED NOVEMBER 1995

- Analog Front-End Integrated Circuit for the 18-Bit Stereo Audio Sigma-Delta Analog-to-Digital Converter TLC320AD58C
- Low Distortion, Low Noise
 - THD+N . . . 0.00056% Typ
 - SNR . . . 108-dB Typ
- Adjustable Signal Gain
- 5-V Single Supply Operation
- Internal Voltage Reference
- Operating Temperature . . . 0°C to 70°C

description

The TL32088 is an analog signal conditioning integrated circuit built using a proprietary Texas Instruments bipolar process. This device is used for the analog signal input stage for the 18-bit, stereo audio, sigma-delta, analog-to-digital converter (ADC) TLC320AD58C exclusively. The TL32088 can convert input signals from single-ended to differential and differential to



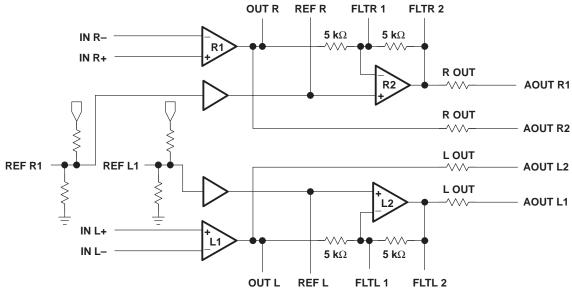
AVAILABLE OPTIONS

	PACKAGE		
T _A	SMALL OUTLINE (NS)		
0°C to 70°C	TL32088CNS		

single-ended. The TL32088 also implements a single-ended to single-ended and differential to differential amplifier buffer. The differential output can be connected to the TLC320AD58C directly. The TLC32088 is composed of high performance amplifiers that offer wide output swing with low distortion and low noise. The reference voltage for the internal amplifier circuit is provided from an internal voltage reference circuit.

The TL32088 provides a wide output swing while maintaining 0.00056% THD+N and 108-dB SNR and, therefore, is ideally suited for high-end audio systems.

functional block diagram





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



TL32088 DIFFERENTIAL ANALOG BUFFER AMPLIFIER FOR THE TLC320AD58

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absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage, AV _{CC} (see Note 1)	7 V
Differential input voltage, V _{ID} (see Note 2)	
Input voltage range, V _I (any input) (see Notes 1 and 3)	0.3 to AV _{CC}
Output voltage, VO	0.3 to AV _{CC}
Output current, IO	20 mA
Duration of short-circuit current at or below 25°C (output shorted to GND)	unlimited
Continuous total power dissipation, P_D ($T_A \le 25^{\circ}C$) (see Note 4)	625 mW
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stq}	−65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltage, are with respect to GND.
 - 2. Differential voltage is at the noninverting input with respect to the inverting input.
 - 3. All input voltage values must not exceed VCC.
 - 4. Derating factor above T_A = 25°C is 10 mW/°C.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, AV _{CC}	4.75	5	5.25	V
Input voltage range, V _I (see Note 5)	1.1		3.9	V
Operating free-air temperature, T _A	0		70	°C

NOTE 5: The output voltage is undetermined when the input voltage exceeds recommended input voltage range.

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS			TYP	MAX	UNIT	
VIO Input offset voltage		V _{IC} = 2.5 V,	T _A = 25°C		1	6	mV	
VIO	input onset voitage	$V_0 = 2.5 \text{ V (AMP L1, R1)}$	$T_A = 0$ °C to 70 °C			7.5	IIIV	
li o	Input offset current	$V_{IC} = 2.5 V,$	T _A = 25°C		5	100		
lo lo	input onset current	$V_0 = 2.5 \text{ V (AMP L1, R1)}$	$T_A = 0$ °C to 70 °C			150	nA	
lin.	Input bias current	V _{IC} = 2.5 V,	T _A = 25°C		20	150	nA	
ΙΒ	input bias current	$V_0 = 2.5 \text{ V (AMP L1, R1)}$	$T_A = 0$ °C to 70 °C			250	IIA	
V10	V _{IC} Common-mode input voltage	V _O ≤ 7.5 mV (AMP L1, R1)	T _A = 25°C	0.9		4.1	V	
VIC		V() ≤ 7.5 IIIV (AIVIP L1, K1)	$T_A = 0$ °C to 70 °C	1.1		3.9		
V _{OM+}	Maximum positive-peak output voltage			4.4			V	
V _{OM} -	Maximum negative-peak output voltage					0.6	V	
A _{vd}	Differential voltage amplification	$V_0 = 2.5 \text{ V} \pm 1 \text{ V} \text{ (AMP L1, R1)}$	T _A = 25°C		60		dB	
CMRR	Common-mode rejection ratio	$V_0 = 2.5 V \pm 1 V (AMP L1, R1)$	T _A = 25°C		85		dB	
V _{ref}	Reference voltage			2.4	2.5	2.6	V	
EG	Gain error	See Note 6				±3%		
r _O	Output resistance		T _A = 25°C		50		Ω	
laa	Complete company (bash abanasa)	V _O = 2.5 V, No load	T _A = 25°C		17	20	mA	
ICC	Supply current (both channels)	$V_O = 2.5 \text{ V}$, No load	$T_A = 0$ °C to 70 °C			25	IIIA	

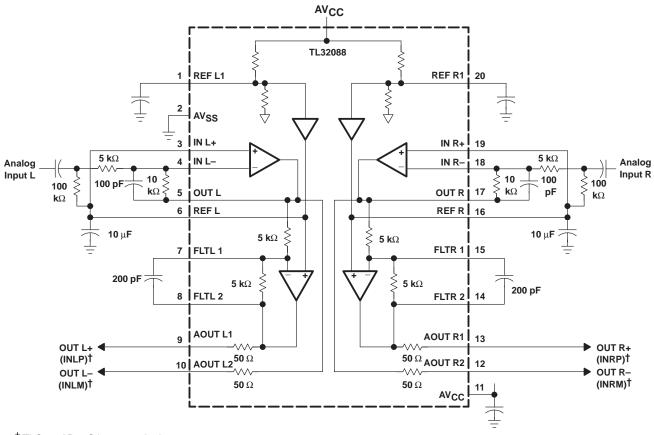
NOTE 6: Gain error is between OUT L and FLTL 1, OUT R and FLTR 1.



operating characteristics over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR	Slew rate	A _V = 1, V _I = 2.5 V + 0.5 V (AMP L1, R1)		3		V/μs
B ₁	Unity-gain bandwidth	AMP L1, R1		7		MHz
SNR	Signal-to-noise ratio (EIAJ)	A-Weighted test circuit (see Figure 2)	104	108		dB
THD+N	Total harmonic distortion plus noise	V _O (PP) = 3.2 V f = 1 kHz, BW = 10 Hz to 20 kHz test circuit		0.00056%	0.001%	
	Crosstalk	$V_{O(PP)} = 3.2 \text{ V}, f = 20 \text{ kHz}$		-125		dB

APPLICATION INFORMATION



[†]TLC320AD58C input terminals.

Figure 1. TL32088 to TLC320AD58C Connections



APPLICATION INFORMATION

Table 1. A-Weighted Data

FREQUENCY	A WEIGHTING (dB)	FREQUENCY	A WEIGHTING (dB)
25	-44.6 ± 2	800	-0.1 ±1
31.5	-39.2 ± 2	1000	0 ±0
40	-34.5 ± 2	1250	0.6 ±1
50	-30.2 ± 2	1600	1.0 ±1
63	-26.1 ±2	2000	1.2 ±1
80	-22.3 ±2	2500	1.2 ±1
100	-19.1 ±1	3150	1.2 ±1
125	-16.1 ±1	4000	1.0 ±1
160	-13.2 ±1	5000	0.5 ±1
200	-10.8 ±1	6300	−0.1 ±1
250	-8.6 ±1	8000	-1.1 ±1
315	-6.5 ±1	10000	-2.4 ±1
400	-4.8 ± 1	12500	-4.2 ±2
500	-3.2 ±1	16000	-6.5 ±2
630	-1.9 ±1	_	_

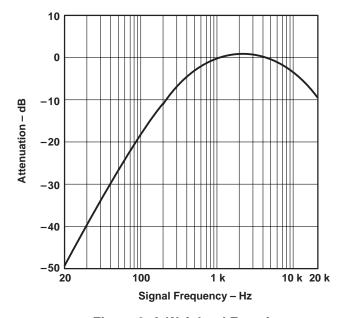


Figure 2. A-Weighted Function



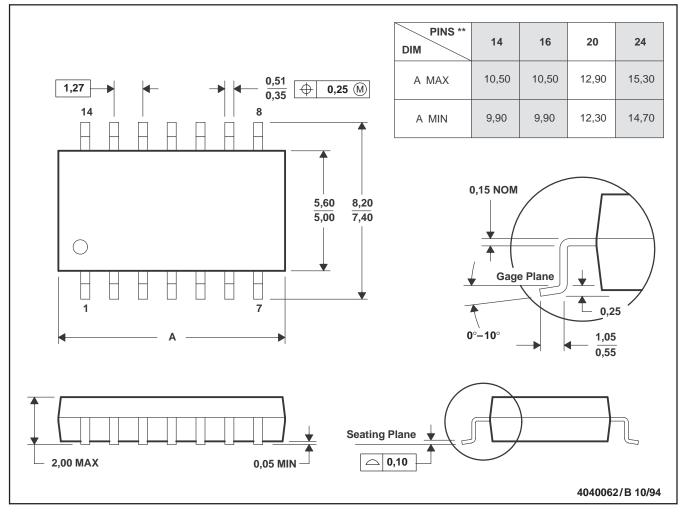
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MECHANICAL DATA

NS (R-PDSO-G**)

14 PIN SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



PACKAGE OPTION ADDENDUM

www.ti.com 4-May-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL32088CNSLE	OBSOLETE	SO	NS	20	TBD	Call TI	Call TI
TL32088CNSR	OBSOLETE	SO	NS	20	TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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